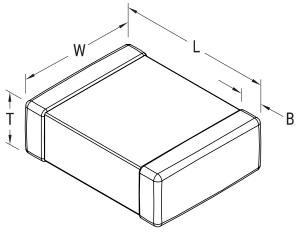


CBR08C939BAGAC

CBR-SMD RF COG, Ceramic, 9.3 pF, +/-0.1 pF, 250 VDC, COG, SMD, Fixed, RF, Ultra High Q, Low ESR, Class I, 0805



Click here for the 3D model.

| General Information | |
|--------------------------|---|
| Series | CBR-SMD RF COG |
| Style | SMD Chip |
| Description | SMD, Fixed, RF, Ultra High Q, Low ESR, Class I |
| Features | Ultra High Q, Low ESR, Class I |
| RoHS | Yes |
| Termination | Tin |
| Marking | No |
| AEC-Q200 | No |
| Typical Component Weight | 12.03 mg |
| Notes | Solder Wave or Solder Reflow. |
| Shelf Life | 78 Weeks |
| MSL | 1 |

| Dimensions | |
|------------|-----------------|
| Chip Size | 0805 |
| L | 2mm +/-0.2mm |
| W | 1.25mm +/-0.2mm |
| Т | 0.85mm +/-0.1mm |
| В | 0.5mm +/-0.2mm |

Packaging Specifications

Packaging Packaging Quantity T&R, 180mm, Plastic Tape 4000

| Specifications | |
|---------------------------------|---------------------|
| Capacitance | 9.3 pF |
| Tolerance | +/-0.1 pF |
| Voltage DC | 250 VDC |
| Dielectric Withstanding Voltage | 500 VDC |
| Temperature Range | -55/+125°C |
| Temp. Coefficient | COG |
| Dissipation Factor | 0.171% |
| Aging Rate | 0% Loss/Decade Hour |
| Insulation Resistance | 10 GOhms |
| Quality Factor | 586 |

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